# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7188244

SUBMISSION TYPE:	
p	Corrective Assignment to correct the SPELLING OF INVENTOR NAME previously recorded on Reel 058939 Frame 0636. Assignor(s) hereby confirms the SPELLING OF INVENTOR YUNZHI LANG TO BE CORRECTED AS YUNZHI LING.

## **CONVEYING PARTY DATA**

Name	Execution Date
YAO WANG	01/10/2022
YUNZHI LING	01/10/2022
YINHUA CUI	01/10/2022
CHUAN HU	01/10/2022
ZIBAI LI	01/10/2022
WEI ZHAO	01/10/2022
ZHITAO CHEN	01/10/2022

### **RECEIVING PARTY DATA**

Name:	INSTITUTE OF SEMICONDUCTORS, GUANGDONG ACADEMY OF SCIENCES
Street Address:	363 CHANGXING ROAD
Internal Address:	TIANHE DISTRICT
City:	GUANGZHOU, GUANGDONG
State/Country:	CHINA
Postal Code:	510650

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17634081

### **CORRESPONDENCE DATA**

**Fax Number:** (616)975-5505

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

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Address Line 2: SUITE 300

Address Line 4: GRAND RAPIDS, MICHIGAN 49546

PATENT REEL: 059352 FRAME: 0749

507141400

ATTORNEY DOCKET NUMBER:	CHO01 P-102	
NAME OF SUBMITTER:	KARL T. ONDERSMA	
SIGNATURE:	/Karl T. Ondersma/	
DATE SIGNED:	02/22/2022	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 2** 

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> PATENT REEL: 059352 FRAME: 0750

## 507120607 02/09/2022

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7167447

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YAO WANG	01/10/2022
YUNZHI LANG	01/10/2022
YINHUA CUI	01/10/2022
CHUAN HU	01/10/2022
ZIBAI LI	01/10/2022
WEI ZHAO	01/10/2022
ZHITAO CHEN	01/10/2022

### **RECEIVING PARTY DATA**

Name:	INSTITUTE OF SEMICONDUCTORS, GUANGDONG ACADEMY OF SCIENCES
Street Address:	363 CHANGXING ROAD
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State/Country:	CHINA
Postal Code:	510650

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17634081

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: CHO01 P-102

NAME OF SUBMITTER: KARL T. ONDERSMA

PATENT REEL: 059352 FRAME: 0751

#### **ASSIGNMENT**

WHEREAS, Yao Wang, Yunzhi Ling, Yinhua Cui, Chuan Hu, Zibai Li, Wei Zhao and Zhitao Chen, residents of China, (hereinafter referred to as Assignors), have invented certain new and useful improvements in a CHIP STACK PACKAGING STRUCTURE AND CHIP STACK PACKAGING METHOD, for which an International Application was filed as PCT/CN2021/111018 on August 5, 2021 and for which an application for United States Letters Patent was executed on even date herewith.

WHEREAS, Institute of Semiconductors, Guangdong Academy of Sciences of China, having a place of business at 363 Changxing Road, Tianhe District, Guangzhou, Guangdong 510650, China, (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of one dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable considerations, Assignors hereby confirm Assignors have and do sell, assign and transfer unto said Assignee the full and exclusive right, title and interest to the said invention in the United States and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefore in the United States and in any and all foreign countries and in and to any and all divisions, reissues, continuations, continuation-in-part, and extensions thereof including the full right to claim for any such applications the benefits of the International Convention.

ASSIGNORS hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Assignee as the owner of the entire right, title and interest in and to the same, for the sole use and behoof of said Assignee, its successors and assigns.

FURTHER, Assignors agree to communicate to said Assignee or its representatives any facts known to Assignors respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitution, renewal, and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Assignee, make all rightful oaths and generally do everything possible to aid said Assignee, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, we have hereunto set our signature on the date appearing next to it.

**RECORDED: 02/22/2022** 

PATENT REEL: 059352 FRAME: 0752